

# **Cascadable Silicon Bipolar MMIC Amplifier**

# **Technical Data**

**MSA-0286** 

#### **Features**

- Cascadable 50  $\Omega$  Gain Block
- **3 dB Bandwidth:** DC to 2.5 GHz
- 12.0 dB Typical Gain at 1.0 GHz
- Unconditionally Stable (k>1)
- Surface Mount Plastic Package
- Tape-and-Reel Packaging Option Available<sup>[1]</sup>

#### Note:

1. Refer to PACKAGING section "Tapeand-Reel Packaging for Surface Mount Semiconductors".

#### **Description**

The MSA-0286 is a high performance silicon bipolar Monolithic Microwave Integrated Circuit (MMIC) housed in a low cost, surface mount plastic package. This MMIC is designed for use as a general purpose 50  $\Omega$  gain block. Typical applications include narrow and broad band IF and RF amplifiers in commercial and industrial applications.

The MSA-series is fabricated using Agilent's 10 GHz  $f_T$ , 25 GHz  $f_{MAX}$ , silicon bipolar MMIC process which uses nitride self-alignment,

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ion implantation, and gold metallization to achieve excellent performance, uniformity and reliability. The use of an external bias resistor for temperature and current stability also allows bias flexibility.

## **Typical Biasing Configuration**



# **MSA-0286 Absolute Maximum Ratings**

Parameter	Absolute Maximum <sup>[1]</sup>			
Device Current	60 mA			
Power Dissipation <sup>[2,3]</sup>	325 mW			
RF Input Power	+13 dBm			
Junction Temperature	150°C			
Storage Temperature	–65 to 150°C			

Thermal Resistance<sup>[2,4]</sup>:  $\theta_{jc} = 105^{\circ}C/W$ 

#### Notes:

- 1. Permanent damage may occur if any of these limits are exceeded.
- 2.  $T_{CASE} = 25^{\circ}C.$
- 3. Derate at 9.5 mW/°C for  $T_C > 116$ °C.

4. See MEASUREMENTS section "Thermal Resistance" for more information.

Symbol	Parameters and Test Conditions:	Units	Min.	Typ.	Max.	
GP	Power Gain $( S_{21} ^2)$	f = 0.1 GHz	dB		12.5	
		f = 1.0  GHz		10.0	12.0	
$\Delta G_P$	Gain Flatness	f = 0.1 to 1.6 GHz	dB		±0.6	
f3 dB	3 dB Bandwidth		GHz		2.5	
VSWR	Input VSWR	f = 0.1 to 3.0 GHz			1.5:1	
	Output VSWR	f = 0.1 to 3.0 GHz			1.4:1	
NF	50 $\Omega$ Noise Figure	f = 1.0  GHz	dB		6.5	
P1 dB	Output Power at 1 dB Gain Compression	f = 1.0  GHz	dBm		4.5	
IP <sub>3</sub>	Third Order Intercept Point	f = 1.0 GHz	dBm		17.0	
tD	Group Delay	f = 1.0  GHz	psec		140	
Vd	Device Voltage		V	4.0	5.0	6.0
dV/dT	Device Voltage Temperature Coefficient		mV/°C		-8.0	

## **Electrical Specifications**<sup>[1]</sup>, $T_A = 25^{\circ}C$

#### Note:

1. The recommended operating current range for this device is 18 to 40 mA. Typical performance as a function of current is on the following page.

# **Part Number Ordering Information**

Part Number	No. of Devices	Container
MSA-0286-TR1	1000	7" Reel
MSA-0286-BLK	100	Antistatic Bag

For more information, see "Tape and Reel Packaging for Semiconductor Devices".

Freg.	S <sub>11</sub>		S <sub>21</sub>		S <sub>12</sub>			S <sub>22</sub>		
GHz	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang	Mag	Ang
0.1	.10	171	12.5	4.22	175	-18.5	.119	1	.16	-5
0.2	.10	161	12.5	4.20	170	-18.3	.121	3	.16	-11
0.4	.10	144	12.4	4.16	159	-18.2	.122	6	.15	-24
0.6	.09	129	12.2	4.09	149	-18.0	.126	6	.15	-36
0.8	.08	119	12.1	4.01	139	-18.0	.127	9	.14	-48
1.0	.08	108	11.9	3.91	129	-17.4	.135	8	.14	-62
1.5	.06	111	11.3	3.67	106	-16.5	.149	12	.11	-99
2.0	.08	141	10.5	3.35	84	-15.7	.164	11	.11	-141
2.5	.14	150	9.6	3.01	67	-14.8	.182	9	.12	-176
3.0	.21	142	8.6	2.68	48	-14.3	.194	5	.13	155
3.5	.29	132	7.5	2.37	30	-14.0	.200	1	.14	140
4.0	.36	121	6.4	2.09	15	-13.5	.211	-3	.16	134
5.0	.50	101	4.1	1.61	-12	-13.3	.216	-12	.20	132

MSA-0286 Typical Scattering Parameters ( $Z_0 = 50 \Omega$ ,  $T_A = 25^{\circ}$ C,  $I_d = 25 m$ A)

A model for this device is available in the DEVICE MODELS section.

# **Typical Performance**, $T_A = 25^{\circ}C$ (unless otherwise noted)



Figure 1. Typical Power Gain vs. Frequency.



Figure 2. Device Current vs. Voltage.



Figure 3. Output Power at 1 dB Gain **Compression, NF and Power Gain vs.** Case Temperature, f = 1.0 GHz,  $I_{d} = 25 \text{ m}\text{A}$ .



Figure 4. Output Power at 1 dB Gain **Compression vs. Frequency.** 



Figure 5. Noise Figure vs. Frequency.



# **86 Plastic Package Dimensions**



DIMENSIONS ARE IN MILLIMETERS (INCHES)

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